Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.(Original): A method for manufacturing a heat resistant flexible laminate comprising a step of laminating a heat resistant adhesive material and a metallic foil by thermal lamination, wherein a film-like protective material is disposed between a pressurized surface and the metallic foil at the time of thermal lamination, and coefficients of linear expansion of the heat resistant adhesive material and the protective material in a temperature range of 200 degrees C to 300 degrees C are within a range of $\alpha_0 \pm 10$ ppm/degree C, when a coefficient of linear expansion of the metallic foil is defined as α_0.

2.(Original): The method for manufacturing a heat resistant flexible laminate according to Claim 1, wherein the thermal lamination is carried out using a thermal lamination device enabling continuous heating and continuous pressurization.

3.(Original): The method for manufacturing a heat resistant flexible laminate according to Claim 2, wherein an adhesive layer of the heat resistant adhesive material has a thermoplastic polyimide resin as a principal component.

4.(Currently Amended): The method for manufacturing a heat resistant flexible laminate according to ~~Claims~~ Claim 1 ~~to 3~~, wherein the protective material consists of a non-thermoplastic polyimide film, and a thickness thereof is not less than 75 micrometers.

5.(Currently Amended): The method for manufacturing a heat resistant flexible laminate according to ~~Claims~~ Claim 1 ~~to 4~~, wherein the metallic foil is a copper foil.

6.(Currently Amended): A heat resistant flexible laminate obtained by the method for manufacturing a heat resistant flexible laminate according to ~~Claims~~ Claim 1 ~~to 5~~.

7.(Original): The heat resistant flexible laminate according to Claim 6, wherein a percentage of dimensional change between before and after removal of at least a portion of the metallic foil by etching is in a range of ±0.05%.